

RF SWITCH CG2163X3

Broadband SPDT RF Switch

DESCRIPTION

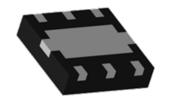
The CG2163X3 is a GaAs MMIC SPDT(<u>Single Pole Double Throw</u>) switch which was developed for 2.4 GHz and 6 GHz dual-band wireless LAN

FEATURES

- Control voltage : VC(H) = 1.8 to 5.0 V (3.0V TYP.) VC(L) = -0.2 to 0.2 V (0V TYP.)
- Low insertion loss:
 L_{ins}1 = 0.40 dB TYP. @ f = 2.4 to 2.5 GHz
 L_{ins}2 = 0.50 dB TYP. @ f = 4.9 to 6.0 GHz
- High isolation:
 ISL1 = 40 dB TYP. @ f = 2.4 to 2.5 GHz
 ISL2 = 31 dB TYP. @ f = 4.9 to 6.0 GHz
- $\begin{array}{ll} & \text{Power handling:} \\ & P_{\text{in(1db)}} = +33 \text{ dBm TYP.} \ @ \ f = 2.5 \text{ GHz} \\ & \text{VC(H)} = 3.0 \text{ V, VC(L)} = 0 \text{ V} \\ & P_{\text{in(1db)}} = +32 \text{ dBm TYP.} \ @ \ f = 6.0 \text{ GHz,} \\ & \text{VC(H)} = 3.0 \text{ V, VC(L)} = 0 \text{ V} \\ \end{array}$

PACKAGE

 6-pin Thin SON Package (XS03) (1.5mm x 1.5mm x 0.37mm)



APPLICATIONS

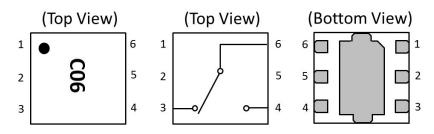
 Dual-band wireless LAN (IEEE802.11a/b/g/n/ac)

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Description
CG2163X3	CG2163X3-C2	6-pin plastic TSON (Pb-Free)	C06	Embossed tape 8 mm wide Pin 1, 6 face the perforation side of the tape MOQ 10 kpcs/reel
CG2163X3-EVAL	CG2163X3-EVAL			Evaluation Board with DC block capacitors, power supply bypass capacitors, and RF and DC connectors MOQ 1



PIN CONFIGURATION AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	GND
2	VC2
3	RF2
4	RF1
5	VC1
6	RFC

Remark Exposed pad: GND

TRUTH TABLE

VC1	VC2	RFC-RF1	RFC-RF2
High	Low	OFF	ON
Low	High	ON	OFF

ABSOLUTE MAXIMUM RATINGS

(TA = +25°C, unless otherwise specified)

(1) 20 0; differential profiled)					
Parameter	Symbol	Rating	Unit		
Control Voltage	VC	6.0 ^{Note 1}	V		
Input Power	Pin	+33.5 ^{Note 2}	dBm		
Operating Ambient Temperature	T _A	-45 ~ +85	°C		
Storage Temperature	T _{stg}	-55 ~ + 150	°C		

Note

1. |VC1 - VC2|≤6.0V

2. 3.0V≤|VC1 - VC2|≤5.0V

RECOMMENDED OPERATING RANGE

(TA = +25°C, unless otherwise specified)

(1A = 125 C, diffess otherwise specified)					
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	f1	2.4	-	2.5	GHz
	f2	4.9	-	6.0	GHz
Switch Control Voltage (H)	VC(H)	+1.8	+3.0	+5.0	V
Switch Control Voltage (L)	VC(L)	-0.2	0	+0.2	V



ELECTRICAL CHARACTERISTICS

(TA=+25°C, VC(H)=3.0V, VC(L)=0V, Zo=50Ω, DC Block Capacitance=4pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss	L _{ins} 1	f = 2.4 to 2.5 GHz	-	0.40	0.60	dB
	L _{ins} 2	f = 4.9 to 6.0 GHz	-	0.50	0.80	dB
Isolation	ISL1	f = 2.4 to 2.5 GHz	37	40	-	dB
	ISL2	f = 4.9 to 6.0 GHz	28	31	-	dB
Return Loss	RL1	f = 2.4 to 2.5 GHz	-	15	-	dB
	RL2	f = 4.9 to 6.0 GHz	-	15	-	dB
1 dB Compression Point Note	P _{in(1dB)}	f = 2.4 to 2.5 GHz, VC(H)=1.8V, VC(L)=0V	-	+29	-	dBm
		f = 2.4 to 2.5 GHz, VC(H)=3.0V, VC(L)=0V	-	+33	-	dBm
		f = 4.9 to 6.0 GHz, VC(H)=1.8V, VC(L)=0V	-	+26	-	dBm
		f = 4.9 to 6.0 GHz VC(H)=3.0V, VC(L)=0V	-	+32	-	dBm
3rd Order Input Intercept Point	IIP3	f = 2.5GHz 2-tone 5MHz Spacing	-	+55	-	dBm
Error Vector Magnitude	EVM	802.11a, 64QAM, 54Mbps Pin≤ + 22dBm	-	2.5	-	%
		802.11g, 64QAM, 54Mbps Pin≤ + 25dBm	-	2.5	-	%
Switch Control Speed	t _{sw}	50% CTL to 90/10%	-	80	-	ns
Switch Control Current	I _{cont}	RF None	-	2	-	μA

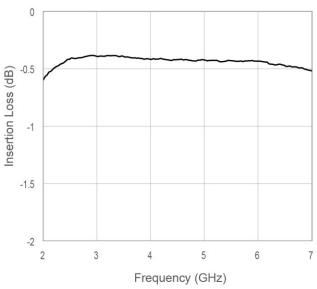
Note Pin_(1dB) is the measured input power level when the insertion loss increases 1dB more than that of the linear range.



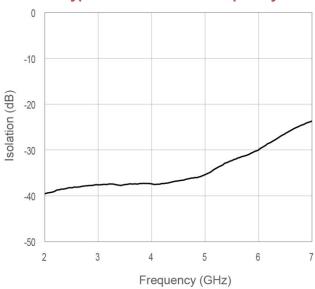
TYPICAL CHARACTERISTICS

(VC(H)=3V, VC(L)=0V, T_A = +25°C, DC Block Capacitance=4pF, through board loss is subtracted in insertion loss data)

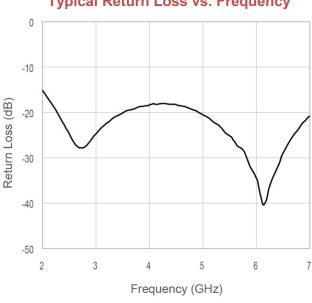
Typical Insertion Loss vs. Frequency



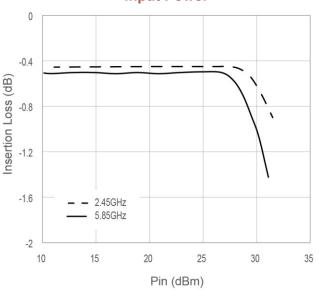
Typical Isolation vs. Frequency



Typical Return Loss vs. Frequency

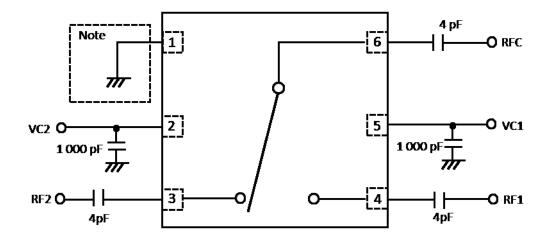


Typical Insertion Loss vs. Input Power





EVALUATION CIRCUIT

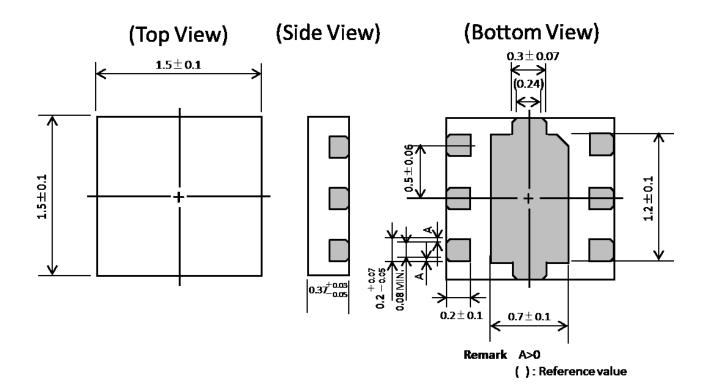


Note: It is recommended to connect the pin directly to the ground, or not to connect the pin to anything.

The application circuits and their parameters are for reference only and are not intended for use in actual designs. DC Blocking Capacitors are required at all RF ports.

PACKAGE DIMENSIONS

6-pin TSON (Unit: mm)





RECOMMENDED SOLDERING CONDITIONS

Recommended Soldering Conditions are available on CEL's Part Summary page under Associated Documents



REVISION HISTORY

Version	Change to current version	Page(s)
CDS-0015-03 (Issue A) February 17, 2016	Initial datasheet	N/A
CDS-0015-03 (Issue B) March 11, 2016	Added Eval Board ordering information	1
CDS-0015-03 (Issue C) March 15, 2016	Updated "Note" definition	3
CDS-0015-03 (Issue D) April 4, 2016	Updated Marking information	1, 2
CDS-0015-03 (Issue E) May 9, 2016	Correction to Truth Table: VC1 and VC2	2
CDS-0015-03 (Issue F) August 11, 2016	Removed "preliminary"	All
CDS-0015-03 (Issue G) January 10, 2017	Revised Electrical Characteristics table Added "Recommended Soldering Conditions" section	3, 5
CDS-0015-06 (Issue H) August 04, 2017	Added Error Vector Magnitude parameter to Electrical Characteristics table Added Typical Characteristics graphs section Revised Evaluation Circuit and added Note	3, 4 ,5



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[CAUTION]

This product uses gallium arsenide (GaAs) of the toxic substance appointed in laws and ordinances. GaAs vapor and powder are hazardous to human health if inhaled or ingested.

- Do not dispose in fire or break up this product.
- Do not chemically make gas or powder with this product.
- When discarding this product, please obey the laws of your country.
- Do not lick the product or in any way allow it to enter the mouth.

[CAUTION]

Although this device is designed to be as robust as possible, ESD (Electrostatic Discharge) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions should be used at all times.

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